

## Acknowledgment

Any document involving a complex technology draws material from a vast number of sources across many continents. While the principal members of the 7-31J Electronic Box Assemblies Task Group of the 7-30 Product Assurance Committee are shown below, it is not possible to include all of those who assisted in the evolution of this standard. To each of them, the members of Global Electronics Association extend their gratitude.

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### 630 A-Team

Global Electronics Association recognizes these A-Teams for their exceptional leadership and effort in the development of this standard. A-Teams are dedicated groups of volunteers who undertake a significant amount of work in standards development on behalf of their group.

A special thank you to the 630 A-Team for their dedication and commitment to this effort. Their support and time during the development of this document is greatly appreciated. A list of members at the time this document was published are listed below.

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## Acknowledgment (cont.)

Karen Denise Smalls EEI Manufacturing Services	Jasbir Bath Koki Solder America	Robert W. Cooke NASA Johnson Space Center
Julie Thompson Electri-Cord Manufacturing Company	Jonathan van Garling Senning Kongsberg Defense & Aerospace AS	Wendell Stephens NASA Marshall Space Flight Center
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## Acknowledgment (cont.)

Udo Welzel Robert Bosch GmbH	Jim Kivell Timberline Manufacturing	Gene Weiner Weiner International Associates
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